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NAME OF INVENTOR(S): Potts	
RECEIPT DATE & SERIAL NO.: Serial No.: 10/055,445 Filing Date: 1/23/2002	
TITLE OF INVENTION: SEMICONDUCTOR WAFER WITH GROUPED INTEGRATED CIRCUIT DIE HAVING INTER-DIE CONNECTIONS FOR GROUP TESTING	
TI FILE NO.: TI-27832	DEPOSIT ACCT. NO.: 20-0668
FAXED: 08/20/2004 DUE: 08/15/2004 ATTY/SEC'Y: WDS/nc	

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Potts
Serial No: 10/055,445
Filed: 1/23/2002
For: SEMICONDUCTOR WAFER WITH GROUPED INTEGRATED CIRCUIT
DIE HAVING INTER-DIE CONNECTIONS FOR GROUP TESTING

Docket No: TI-27832
Examiner: Geyer, Scott B.
Art Unit: 2829

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AMENDMENT UNDER 37 C.F.R. § 1.115

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Dear Sir:

Responsive to the Office Action mailed June 15, 2004 in connection with the
above identified application, Applicants respectfully submit the following amendments
and remarks.